



JAPANESE PATENT OFFICE

AUG 2 2001

PATENT ABSTRACTS OF JAPAN

(11) Publication number: 2000049195 A

(43) Date of publication of application: 18.02.00

(51) Int. Cl

H01L 21/60

(21) Application number: 10216848

(22) Date of filing: 31.07.98

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(54) PRODUCING METHOD OF ELECTRONIC  
COMPONENT MEMBER

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(57) Abstract:

PROBLEM TO BE SOLVED: To provide a producing method for a member of electronic components.

SOLUTION: Resist patterns 4, 5 are formed individually on metallic foils 2, 3 which are laminated on both sides of a polyimide film 1, and both of the metallic foils 2, 3 are simultaneously etched in an etching liquid, and then the resist patterns 4, 5 are exfoliated. After that, the polyimide film 1 is patterned by plasma etching with the use of only the metallic foil 3 as a mask, and then the metallic foil 3 which has been used as a mask is eliminated. As a result, as a member for electronic components, a laminated body 8 can be obtained, which consists of the patterned polyimide film 1 and the patterned metallic foil 2. Because of only once requirement for plate making, it is possible to produce the member for electronic components at lower costs, and it is also possible to obtain the high quality member which is laminated by the polyimide film pattern and the metallic foil pattern at their high positional precision.

